

ABSTRACT

An adhesive material and a pressure sensitive adhesive film containing the same of the present invention are characterized in that they satisfy the following requirements (a) and (b). These adhesive material and pressure sensitive adhesive film of the present invention exhibit excellent stability against not only light and heat but also various chemicals. Consequently, they are suitable applications in surface protection uses, transport storage uses, heating treatment uses, grinding/polishing uses, cutting processing uses and transport/storage uses in the fields of electronic/semiconductor materials, optical/display materials and the like, where demands for performances and qualities are strict. The above requirements are: (a) an olefinic polymer is contained, and (b) by measurement according to a differential scanning calorimetry test, the melting temperature T_m is in the range of 80°C to 180°C and the heat of fusion ΔH is at least 1 J/g.